COMPLIANT

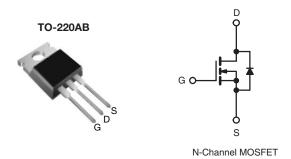
HALOGEN

FREE



# **D Series Power MOSFET**

PRODUCT SUMMA	RY	
V <sub>DS</sub> (V) at T <sub>J</sub> max.	450	)
R <sub>DS(on)</sub> max. at 25 °C (Ω)	V <sub>GS</sub> = 10 V	0.17
Q <sub>g</sub> max. (nC)	88	
Q <sub>gs</sub> (nC)	12	
Q <sub>gd</sub> (nC)	23	
Configuration	Sing	le



#### **FEATURES**

- Optimal Design
  - Low Area Specific On-Resistance
  - Low Input Capacitance (Ciss)
  - Reduced Capacitive Switching Losses
  - High Body Diode Ruggedness
  - Avalanche Energy Rated (UIS)
- · Optimal Efficiency and Operation
  - Low Cost
  - Simple Gate Drive Circuitry
  - Low Figure-of-Merit (FOM): Ron x Qa
  - Fast Switching
- Compliant to RoHS Directive 2011/65/EU

#### Note

\* Pb containing terminations are not RoHS compliant, exemptions may apply

#### **APPLICATIONS**

- Consumer Electronics
  - Displays (LCD or Plasma TV)
- Lighting
- Industrial
  - Welding
  - Induction Heating
  - Motor Drives
  - Battery Chargers
- SMPS

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	SiHP25N40D-E3
Lead (Pb)-free and Halogen-free	SiHP25N40D-GE3

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		$V_{DS}$	400			
Gate-Source Voltage	.,	± 30	V			
Gate-Source Voltage AC (f > 1 Hz)	$V_{GS}$	30				
Continuous Drain Current (T <sub>J</sub> = 150 °C)	$V_{GS}$ at 10 V $T_{C} = 25 ^{\circ}C$ $T_{C} = 100 ^{\circ}C$	I <sub>D</sub>	25	А		
			16			
Pulsed Drain Current <sup>a</sup>	I <sub>DM</sub>	78				
Linear Derating Factor			2.2	W/°C		
Single Pulse Avalanche Energy <sup>b</sup>	E <sub>AS</sub>	556	mJ			
Maximum Power Dissipation	$P_{D}$	278	W			
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 150	°C			
Drain-Source Voltage Slope	T <sub>J</sub> = 125 °C	dV/dt	24	V/ns		
Reverse Diode dV/dt <sup>d</sup>	uv/ut	0.6	V/IIS			
Soldering Recommendations (Peak Temperature)	for 10 s		300 <sup>c</sup>	°C		

### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b.  $V_{DD}$  = 50 V, starting  $T_J$  = 25 °C, L = 2.3 mH,  $R_g$  = 25  $\Omega$ ,  $I_{AS}$  = 17 A.
- c. 1.6 mm from case.
- d.  $I_{SD} \le I_D$ , starting  $T_J = 25$  °C.



# Vishay Siliconix

THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	62	°C/W
Maximum Junction-to-Case (Drain)	$R_{thJC}$	-	0.45	C/VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static					•	•	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub>	= 0 V, I <sub>D</sub> = 250 μA	400	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I <sub>D</sub> = 250 μA	=.	0.5	-	V/°C
Gate-Source Threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> :	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	3	-	5	V
Gate-Source Leakage	I <sub>GSS</sub>		V <sub>GS</sub> = ± 30 V	-	-	± 100	nA
7 0 1 1/1 5 1 0 1		V <sub>DS</sub> = 400 V, V <sub>GS</sub> = 0 V	-	-	1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 320 \	V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	10	μA
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 13 A	-	0.14	0.17	Ω
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub>	= 50 V, I <sub>D</sub> = 13 A	-	7.4	-	S
Dynamic						•	
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0 V$ ,		-	1707	-	pF
Output Capacitance	C <sub>oss</sub>	1	$V_{DS} = 0.0$ , $V_{DS} = 100 \text{ V}$ ,		177	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		f = 1 MHz	-	19	-	
Total Gate Charge	Qg		<sub>SS</sub> = 10 V	-	44	88	nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V		-	12	-	
Gate-Drain Charge	$Q_{gd}$			=.	23	-	
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{DD} = 320 \text{ V}, I_{D} = 13 \text{ A},$ $V_{GS} = 10 \text{ V}, R_{g} = 24.6 \Omega$		=.	21	42	- ns
Rise Time	t <sub>r</sub>			-	57	86	
Turn-Off Delay Time	t <sub>d(off)</sub>			-	40	80	
Fall Time	t <sub>f</sub>			=.	37	74	
Gate Input Resistance	$R_g$	f = 1 MHz, open drain		-	1.8	-	Ω
<b>Drain-Source Body Diode Characteristic</b>	S						
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET sym showing the	MOSFET symbol showing the		-	24	
Pulsed Diode Forward Current	I <sub>SM</sub>	integral reverse p - n junction diode		-	-	78	A
Diode Forward Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 13 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse Recovery Time	t <sub>rr</sub>			-	353	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>	$T_J = 25 ^{\circ}\text{C}, I_F = I_S = 13 \text{A},$ $dI/dt = 100 \text{A/}\mu\text{s}, V_R = 20 \text{V}$		-	4.4	-	μC
Reverse Recovery Current	I <sub>RRM</sub>			_	24	_	Α



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

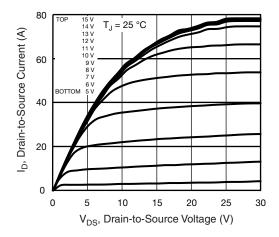


Fig. 1 - Typical Output Characteristics

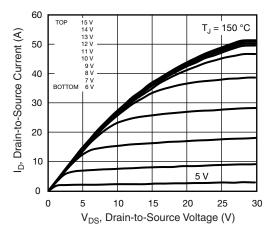


Fig. 2 - Typical Output Characteristics

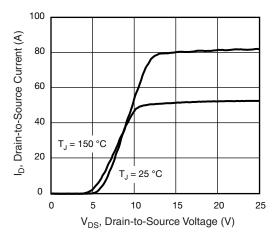


Fig. 3 - Typical Transfer Characteristics

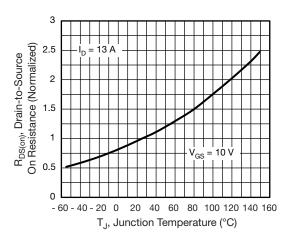


Fig. 4 - Normalized On-Resistance vs. Temperature

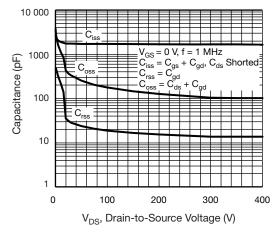


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

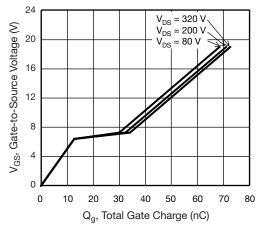


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



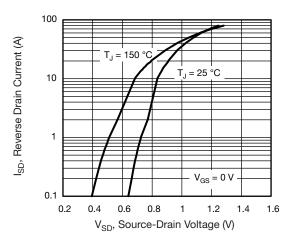


Fig. 7 - Typical Source-Drain Diode Forward Voltage

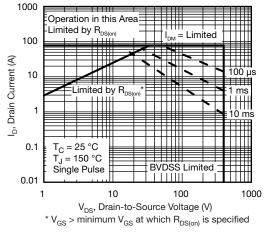


Fig. 8 - Maximum Safe Operating Area

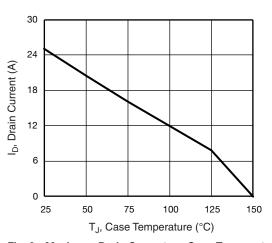


Fig. 9 - Maximum Drain Current vs. Case Temperature

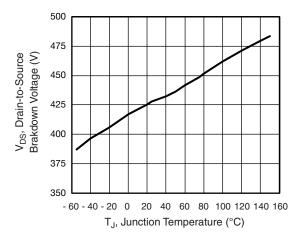


Fig. 10 - Temperature vs. Drain-to-Source Voltage

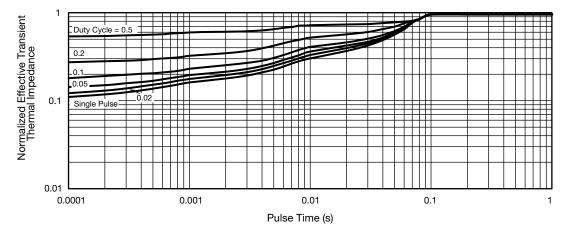


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case

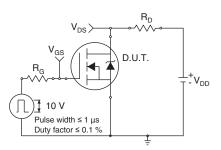


Fig. 12 - Switching Time Test Circuit

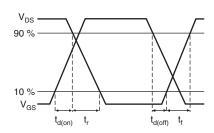


Fig. 13 - Switching Time Waveforms

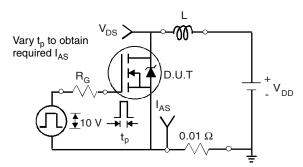


Fig. 14 - Unclamped Inductive Test Circuit

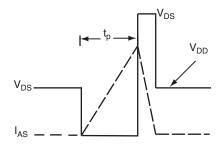


Fig. 15 - Unclamped Inductive Waveforms

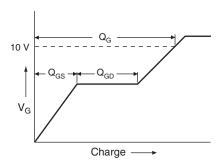


Fig. 16 - Basic Gate Charge Waveform

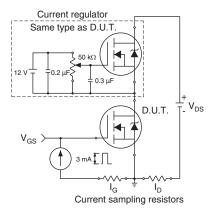
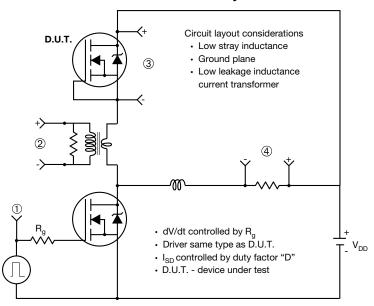


Fig. 17 - Gate Charge Test Circuit



## Peak Diode Recovery dV/dt Test Circuit



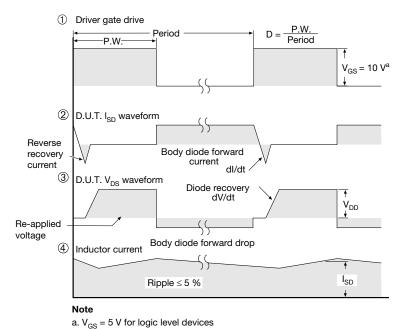
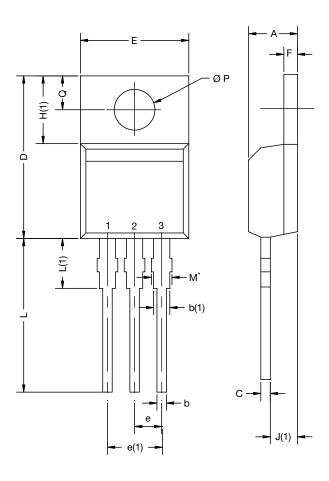


Fig. 18 - For N-Channel

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# TO-220-1



DIM.	MILLIM	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.	
Α	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
E	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØP	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	

## Note

DWG: 6031

•  $M^* = 0.052$  inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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Vishay

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